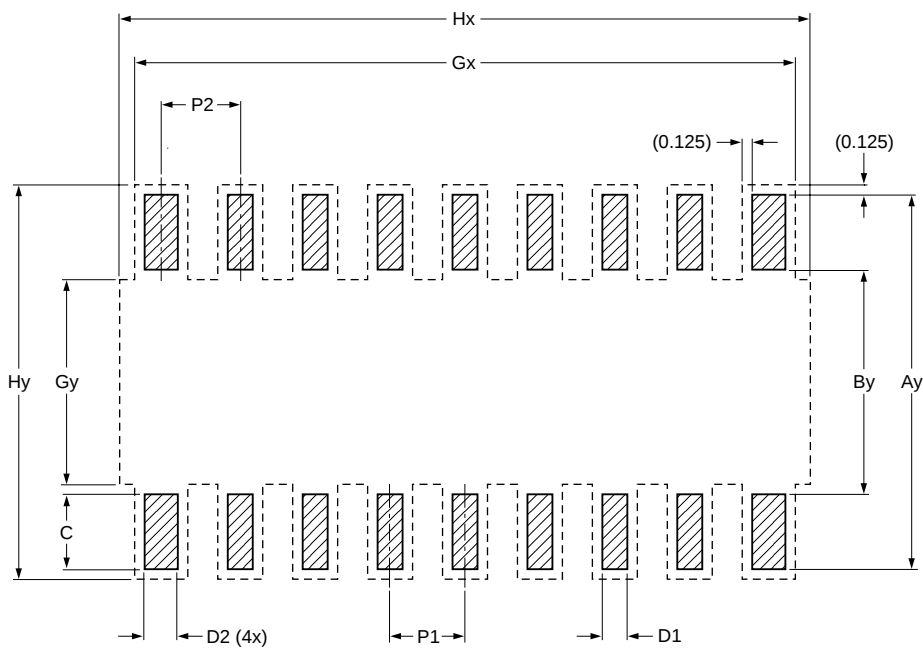


Footprint information for reflow soldering of TSSOP56 package

SOT481-2



Generic footprint pattern  
Refer to the package outline drawing for actual layout

 solder land  
- - - - occupied area

DIMENSIONS in mm

| P1    | P2    | Ay    | By    | C     | D1    | D2    | Gx     | Gy    | Hx     | Hy    |
|-------|-------|-------|-------|-------|-------|-------|--------|-------|--------|-------|
| 0.400 | 0.430 | 7.200 | 4.500 | 1.350 | 0.240 | 0.300 | 11.410 | 5.300 | 13.300 | 7.450 |